

PRODUCT SPECIFICATION

Model No: BOH-NWS4-60

For reference only.

Subject to change maybe necessary in a limited number of cases

Descriptions:

Double Chip on AlN Model

• AlN Substrate

Emitting Color : White

• Viewing Angle: 120°





LED 胶体为软硅胶封装,请避免外力碰撞。

CUSTOMER APPROVED APPROVED BY SIGNATURES		CHECKED BY	PREPARED BY
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■ Applications

- Automotive Headlamp
- Day time running light
- Fog lamp
- Working lamp
- Cornering light

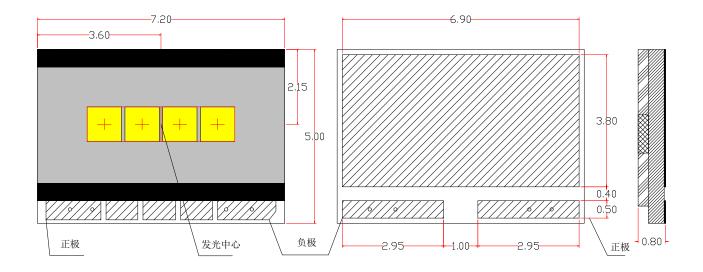
■ Device Selection Guide

Model No.		Chip Epoxy Co		
model ivo.	Material	Emitting Color	LPOXY COTO	
BOH-NWS4-60	InGaN	White	Yellow Diffused	

LED 胶体为软硅胶封装,运输、装配避免外力碰撞白色胶体和黄色荧光片。

■ Package Outline Dimensions

Dimensions: 7.2(L) \times 5.0(W) \times 0.8(H) mm.



Emitting area: $1.0*4.3\pm0.1$ mm

Note:

- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are \pm 0.2mm.



■ Absolute Maximum Ratings (Ta=25° C)

Items	Symbol	Absolute Maximum Ratings	Unit
Power Dissipation	P_{d}	14	W
Junction Temperature	Tj	150	$^{\circ}$ C
Forward Current(DC)*	$I_{\scriptscriptstyle F}$	100~1200	mA
Operation Temperature	$T_{ m opr}$	−40 [~] +125	$^{\circ}$ C
Storage Temperature	$T_{ m stg}$	−40 [~] +125	$^{\circ}$ C
Wavelength	Wp	435 ~ 460	nm
Wavelength	Wd	450 ~600	nm
Ra	Ra	≥65	
Thermal resistance junction/board*	Rth	Typ 0.8 (max 1.2)	k/w
ESD (IEC-61000-4-2)	ESD	8	KV
Lead Soldering Temperature	$T_{\rm sol}$	260℃ for 10 Seconds	

NOTE: For long-term performance, the drive currents between 100 mA and 1000 mA are recommended, Ts<125 $^{\circ}$ C.

If the the drive currents is different with our condition ,Please contact our customer service.

PCB temperature assurance \leq 125°C, test point distance within 2 mm LED solder.

PCB 温度确保<125℃,测试点距离 LED 焊锡 2mm 内。

■Typical Electrical & Optical Characteristics (Ta=25°C)

Items	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	$V_{\scriptscriptstyle F}$	$I_{\scriptscriptstyle F}\!\!=\!\!1000\text{mA}$	10.8	12.8	14	V
Reverse Current	$I_{\scriptscriptstyle R}$	VR=-5V			5	μА
Chromaticity Coordinate	(x, y)	I _F =1000mA	0. 31/0. 31	0. 325/0. 335	0. 345/ 0. 367	
Color Temperature	CCT	$I_{\scriptscriptstyle F}\!\!=\!\!1000\text{mA}$	5000	6000		K
Luminous Flux	Фу	$I_{\scriptscriptstyle F}\!\!=\!\!1000\text{mA}$	1000	1320		Lm
50% Power Angle	2 θ 1/2	$I_{\scriptscriptstyle F}\!\!=\!\!1000\text{mA}$		120		Deg

\blacksquare Ranks Combination ($I_F = 1000 \text{mA}$)

Rank	L7	L8	L9
Luminous Flux (Lm)	1080 ~1200	1200 ~1440	1440 ~1800

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Notes:

- *Tolerance of measurement of Luminous Flux is $\pm 15\%$;
- *Tolerance of measurement of forward voltage is \pm 0.5V;
- *Chromaticity Coordinate s measurement allowance: ± 0.015 .

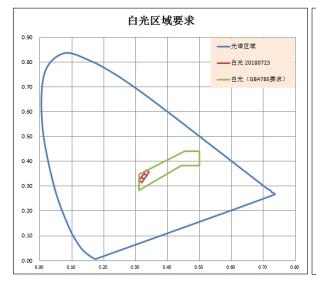
■ Chromaticity coordinate(IF=1000mA)

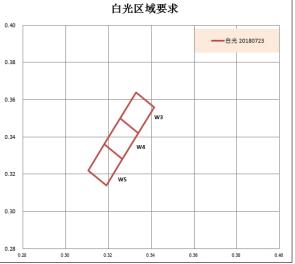
白光

	Х	У
	0.343	0.359
	0.3345	0.367
W3	0.327	0.353
	0.3355	0.345
	0.343	0.359
	0.3355	0.345
	0.327	0.353
W4	0.3195	0.339
	0.328	0.331
	0.3355	0.345

	X	У
	0.328	0.331
	0.3195	0.339
W5	0.312	0.325
	0.3205	0.317
	0.328	0.331

■CIE Graph





Note:

- 1. Percentage of red:>5% acc. to GB 25991 regulation.
- 2. Percentage of UV: $<\!10\text{--}5$ W/lm acc. to GB 25991 regulation.
- 3, Acc. to white area GB 4785.



■ Reliability

1) Test Items and Results:

Classifi- cation	Test Item	Standard Test Method	Test Conditions	Duration	Units Tested	Number Of Damaged
Operating Life Test # JIS7021:B4 MIL-STD-202:107D MIL-STD-750:1026		Ta=85±5℃, IF=1200mA *	1000 Hrs	11	0/11	
Life	*	JESD22-A101	Ta=85±5°C RH=85±5%RH IF=1200mA *	1000 Hrs	11	0/11
LI .	High JIS7021:B10 Temperatur MIL-STD-202:210A e Storage MIL-STD-750:2031		Ta=125±5℃	1000 Hrs	11	0/11
Environment Test	Temp. & Humidity Test	JIS7021:B11 MIL-STD-202:103D	Ta=85±5°C RH=85±5%RH	1000Hrs	11	0/11
Envii	Thermal Shock Test	JIS7021B4 MIL-STD-202:107D MIL-STD-750:1026	-40°C ← - →125°C 15min 10sec 15min	1000 Cycles	11	0/11
	ESD	MIL-STD-105E HBM	8Kv	10 Cycles	11	0/11
Solderi ng Test	Resistance to soldering	_	Tsol=260±5℃, 10sec	Twice	22	0/22

^{*} Reliability items are tested under good thermal management with Tj<150°C, Ts<125°C. PCB temperature assurance < 125°C, test point distance within 2 mm LED solder.

PCB 温度确保<125℃,测试点距离 LED 焊锡 2mm 内。

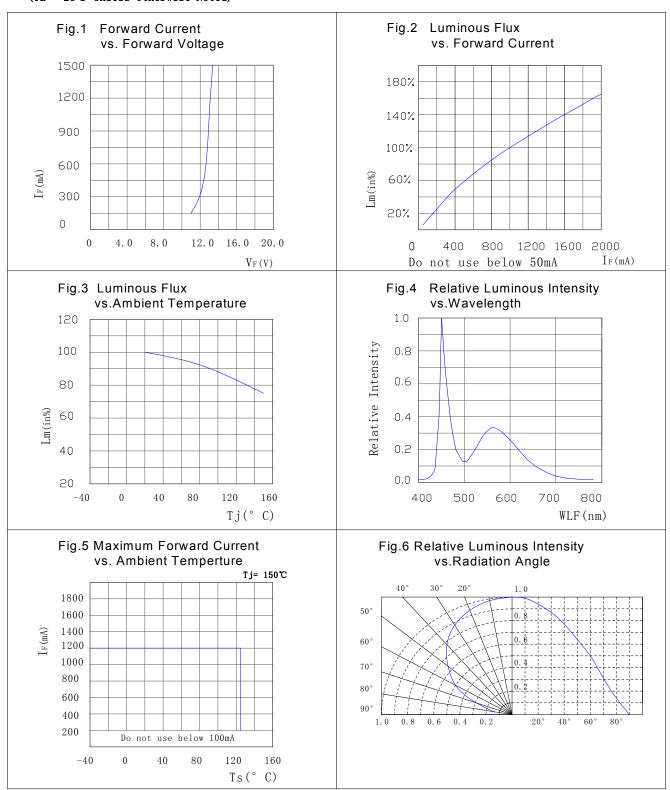
■ 2) Criteria for Judge The Damage:

Items	Symbol	Condition	Criteria f	for Judge	
1 tems	Зушоот	Collaition	Min.	Max.	
Forward Voltage	$V_{\scriptscriptstyle F}$	$I_{\scriptscriptstyle F} = 1000 \text{mA}$		initial value x 1.2	
Reverse Current	$I_{\scriptscriptstyle R}$	V _R =5V		not designed for reverse operation	
Luminous Flux (Lm)	$I_{\rm v}$	$I_{\rm F}=1000{\rm mA}$	initial value x 0.85		

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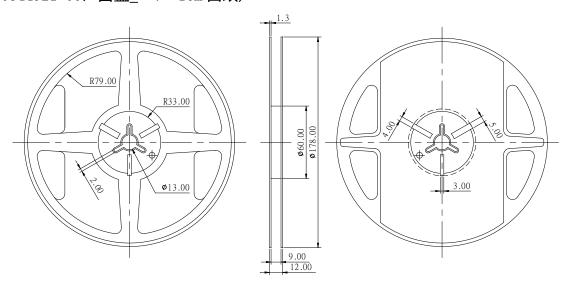


■ Typical Electrical / Optical Characteristics Curves (Ta = 25°C Unless Otherwise Noted)

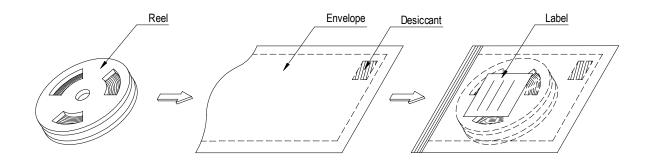




■ Reel Specification: (10344921-00, 圆盘_Φ7×16m 图纸)



- \blacksquare Taping Specification (200, 500 , 1000, 2000pcs / reel)
- ■Packing Type





■Precautions For Use

1. Over - current - proof

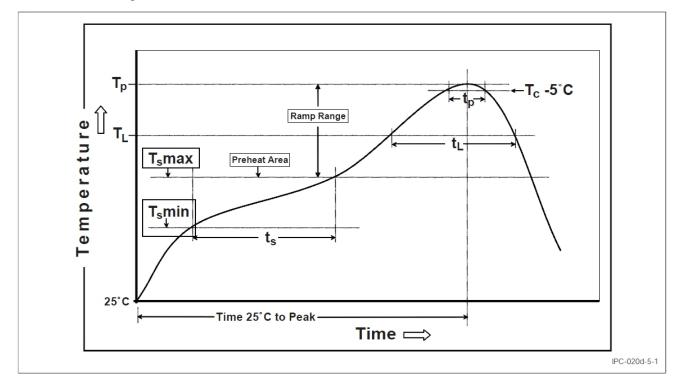
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

2. Storage

- $2.1\ \mathrm{Do}\ \mathrm{not}\ \mathrm{open}\ \mathrm{moisture}\ \mathrm{proof}\ \mathrm{bag}\ \mathrm{before}\ \mathrm{the}\ \mathrm{products}\ \mathrm{are}\ \mathrm{ready}\ \mathrm{to}\ \mathrm{use}.$
- 2.2 The LEDS should be kept at 30°C or less and 70%RH or less, and the storage life limits are 12 months
- 2.3 Product complies to MSL Level 2 acc. to JEDEC J-STD-020E.

3. Soldering

3.1 Reflow Soldering / Time



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Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
Preheat & Soak			
Temperature Min (Tsmin)	100° C	150° C	
Temperature Max (Tsmax)	150° C	200° C	
Time (Tsmin to Tsmax) (ts)	60-120 seconds	60-120 seconds	
Average ramp-up rate	3° C/second max.	3° C/second max.	
(Tsmax to Tp)	5 C/ Second max.	o c/ second max.	
Liquidous Temperature (TL)	183° C/60-150 seconds	217° C/60-150 seconds	
Time at Liquidous (tL)	103 C/00-130 Seconds		
Peak Package Body Temperature (Tp)*	235° C max.	260° C max.	
Time (tp)** within 5° C of the specified	10 seconds max	10 generals were	
classification Temperature (Tc)	TO Seconds max	10 seconds max	
Average ramp-down Rate (Tp to	6° C/second max.	6° C/second max.	
Tsmax)	U C/Second max.	O C/Second max.	
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.	

- 3.2 Reflow soldering should not be done more than two times;
- 3.3 While soldering, do not put stress on the LEDs during heating;
- 3.4After soldering, do not warp the circuit board.

4. Caution in ESD

- 4.1 Electrostatic discharge (ESD) and surge current (EOS) can damage LEDs.
- 4.2 An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs
- 4.3 All devices equipment and machinery must be properly grounded.

5. Other

- 5.1 Above specification may be changed without notice. BYD will reserve authority on material change for above specification
- 5.2 When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification. BYD assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification

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RESTRICTIONS ON PRODUCT USE

- The information contained herein is subject to change without notice.
- BYD Semiconductor Company Limited exerts the greatest possible effort to ensure high quality and reliability. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing products, to comply with the standards of safety in making a safe design for the entire system, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue. In developing your designs, please ensure that products are used within specified operating ranges as set forth in the most recent products specifications.
- The products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of

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